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NEDER28.001APC

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Kuznetsov, et al.

Appl. No. : Unknown

Filed : Herewith

For : METHOD FOR  
TRANSFERRING WAFERS  
AND RING

Examiner : Unknown

) Group Art Unit Unknown

) I hereby certify that this correspondence and all  
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) Commissioner for Patents, Washington, D.C.  
) 20231, on

) 11/6/01  
) (Date)  
) *Gordon H. Olson*  
) Gordon H. Olson, Reg. No. 20,319

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

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Dear Sir:

Prior to examination of the above-captioned application, please amend the application as follows:

IN THE SPECIFICATION:

Please amend the specification, published as International Application WO 00/68977, as follows:

On page 1, line 2, please insert --Field of the Invention--.

Please amend the paragraph beginning on page 1, line 3, as follows:

The present invention relates to a method of transferring a wafer between a thermal treatment chamber and a thermal treatment installation.

Background of the Invention

RECEIVED

FEB 20 2004

GROUP 3600